

Dual N-Channel 60 V (D-S) 175 °C MOSFET

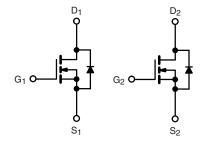
PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.040			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.055			
I _D (A) per leg	7			
Configuration	Dual			

SO-8 Dual $\begin{array}{c} D_2 \\ D_2 \\ D_1 \\ 7 \\ 8 \\ \end{array}$ $\begin{array}{c} D_2 \\ 5 \\ \end{array}$ $\begin{array}{c} D_3 \\ G_2 \\ \end{array}$ $\begin{array}{c} 3 \\ G_2 \\ \end{array}$ $\begin{array}{c} G_2 \\ \end{array}$ $\begin{array}{c} Top \ View \\ \end{array}$

FEATURES

- TrenchFET® power MOSFET
- 100 % R_q and UIS tested





N-Channel MOSFET N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C	1	7		
	T _C = 125 °C	- I _D	4		
Continuous Source Current (Diode Conduction) ^a		I _S	3.6	Α	
Pulsed Drain Current ^b		I _{DM}	28		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	18		
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	16.2	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	р	4	W	
	T _C = 125 °C	P _D	1.3	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	110	°C/W		
Junction-to-Foot (Drain)		R_{thJF}	34	C/VV		

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. When mounted on 1" square PCB (FR4 material).

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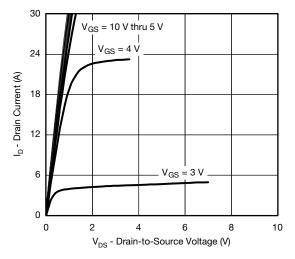
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$		1.5	2.0	2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	μА
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$	-	-	150	
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = 10 \text{ V}$	$V_{DS} \ge 5 V$	20	-	-	Α
		V _{GS} = 10 V	I _D = 4.5 A-		0.028	0.040	Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 4.5 A, T _J = 125 °C	-	-	0.066	
Zrani Godines en Glats Hesiolanies	1 103(011)	V _{GS} = 10 V	I _D = 4.5 A, T _J = 175 °C	-	-	0.081	
		$V_{GS} = 4.5 \text{ V}$	I _D = 4 A-		0.030	0.055	
Forward Transconductance f	9fs	$V_{DS} = 15 \text{ V}, I_D = 4.5 \text{ A}$		-	15	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			-	600	750	pF
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	110	140	
Reverse Transfer Capacitance	C _{rss}			-	50	62	
Total Gate Charge ^c	Qg			-	11.7	18	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_D = 5.3 \text{ A}$	-	1.8	2.7	nC
Gate-Drain Charge ^c	Q_{gd}			-	2.8	4.2]
Gate Resistance	R_g		f = 1 MHz	1.3	-	6	Ω
Turn-On Delay Time ^c	t _{d(on)}				7	11	
Rise Time °	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_L = 6.8 \Omega$ $I_D \cong 4.4 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		-	3.3	5	- ns
Turn-Off Delay Time ^c	t _{d(off)}			-	22.4	33.5	
Fall Time ^c	t _f			-	2.1	3.2	
Source-Drain Diode Ratings and Chara	acteristics b						
Pulsed Current ^a	I _{SM}			-	-	28	Α
Forward Voltage	V _{SD}	I _F = 2 A, V _{GS} = 0 V		-	0.75	1.1	V

Notes

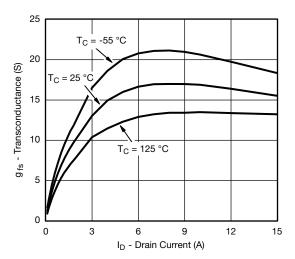
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing. c. Independent of operating temperature.



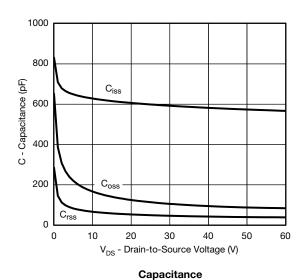
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)

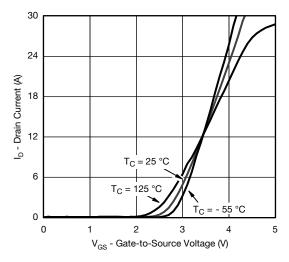


Output Characteristics

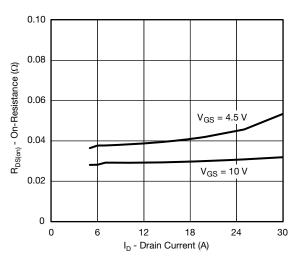


Transconductance

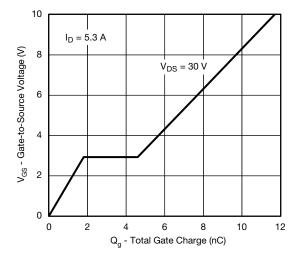




Transfer Characteristics



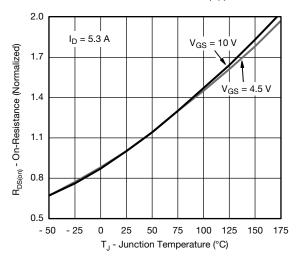
On-Resistance vs. Drain Current



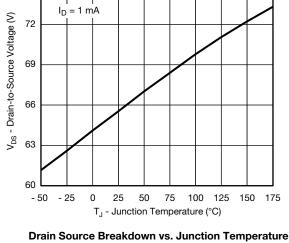
Gate Charge

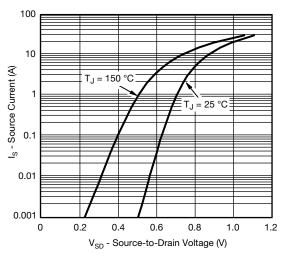


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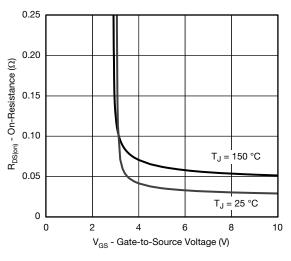


On-Resistance vs. Junction Temperature

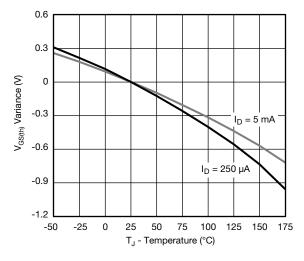




Source Drain Diode Forward Voltage



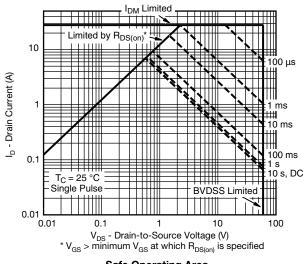
On-Resistance vs. Gate-to-Source Voltage



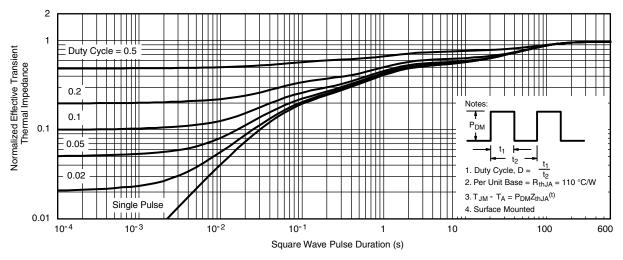
Threshold Voltage



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



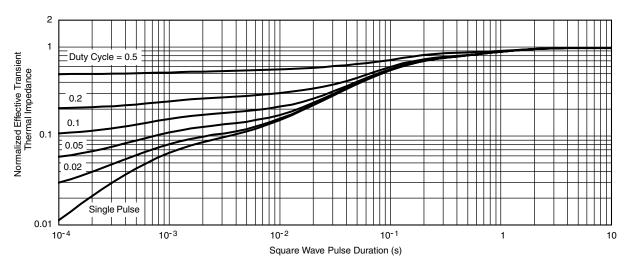
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



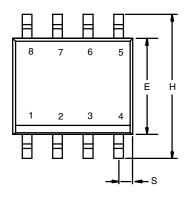
THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)

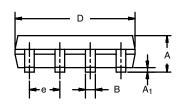


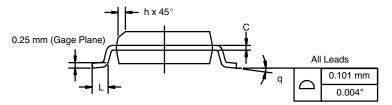
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







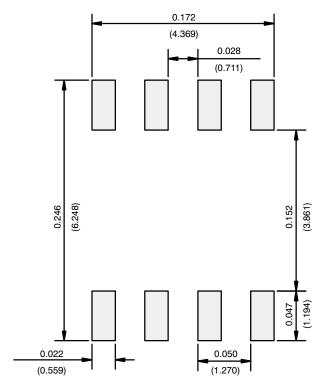
	MILLIM	IETERS	INCHES		
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C 06527 Pay 1 11 Cap 06					

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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